

RoHS

Specification

规格书

Customer Name : _____

客户名称 :

Customer P/N : _____

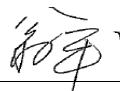
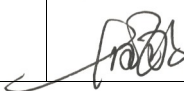

客户品号 :

Factory P/N : HL-PST-1608IR1C-L4

公司品号 :

Sending Date : _____

送样日期 :

Client approval 客户审核		Hongli approval 鸿利智汇审核		
Approval 核准	Audit 确认	Approval 核准	Audit 确认	Confirmation 制作
				
<input type="checkbox"/> Qualified 接受	<input type="checkbox"/> Disqualified 不接受	DATE: 日期:		

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注: 1. 此规格书以中英文方式书写, 若有冲突以中文版本为准文本.

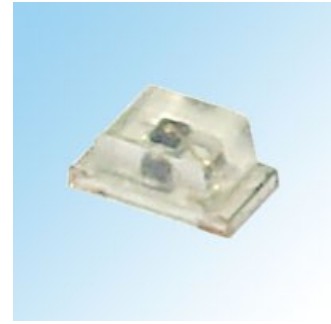
2. 此规格书的最终解释权归鸿利智汇集团股份有限公司

3. 此规格书的有效期限为两年, 自盖章或签字之日起计算, 期满时双方可以续签协议, 但应采用书面形式

HL-PST-1608IR1C-L4

Features(特征)

- Extremely wide viewing angle. (宽的发光角度)
- Suitable for all SMT assembly and solder process. (适用于所有的SMT组装和焊接工艺)
- Available on tape and reel. (适用于载带及卷轴)
- Moisture sensitivity level: Level 4. (防潮等级 Level 4)
- RoHS compliant. (RoHS 认证)



Description (描述)

IR1C-L4 made with GaAs infrared chips

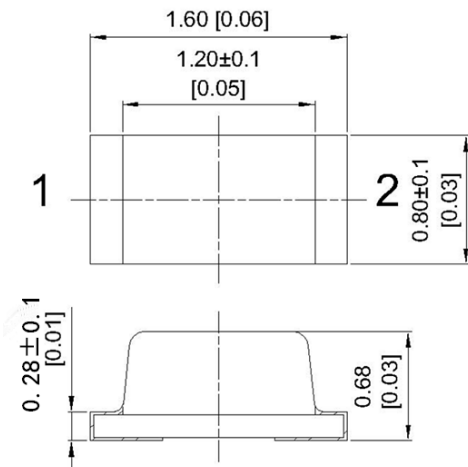
IR1C-L4 由GaAs元素组成的芯片



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

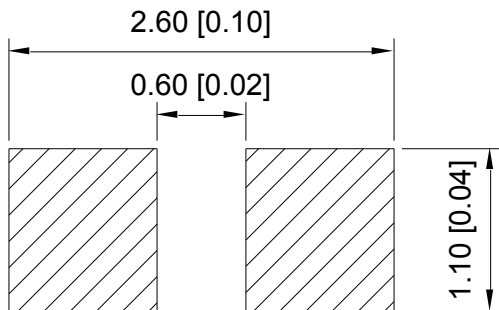
注意：操作时应注意静电敏感
释放设备装置

Package Dimensions (封装尺寸)

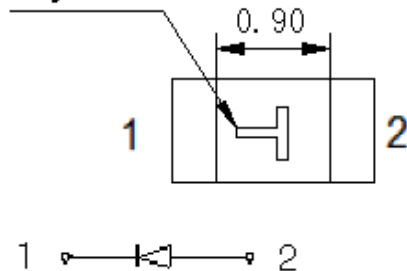


Recommended Soldering Pattern

(建议焊盘尺寸图)



Polarity Mark



Notes: (备注)

1. Mark the size of the unit is mm.marked in brackets (标注尺寸单位为毫米,括号内标注为英寸)

2. All dimensions allow tolerance ±0.1mm (所有尺寸允许公差±0.1mm)

HL-PST-1608IR1C-L4

Electrical / Optical Characteristics at Ta=25°C 电性与光学特性

Parameter (参数)	Symbol (符号)	Min. (最小)	Typ. (平均)	Max. (最大)	Units (单位)	Test Conditions 测试条件
Forward Voltage 正向电压	V _F	0.8	1.2	--	V	I _F =20mA
Reverse Current 反向电流	I _R	--	--	10	uA	V _R = 5V
Peak Wavelength 峰值波长	λ _p	--	940	--	nm	I _F =20mA
Spectrum width of Half value 半波光谱宽值	Δλ	--	50	--	nm	I _F =20mA
Viewing Angle 可视角度	1/2θ	--	120	--	deg	I _F =20mA

Parameter (参数)	Symbol (符号)	Min. (最小)	Typ. (平均)	Max. (最大)	Units (单位)	Test Conditions 测试条件
辐射强度	I _e	0.3	—	0.8	mW /sr	I _F =20mA
		0.8	—	1.3		
		1.3	—	1.8		

Absolute Maximum Ratings at Ta=25°C 绝对最大额定值

Parameter (参数)	Symbol (符号)	Infrared (值)	Units (单位)
Power Dissipation (功耗)	P _d	100	mW
DC Forward Current (正向电流)	I _F	50	mA
Reverse Voltage 反向电压	V _R	5	V
Operating/Storage Temperature (操作温度)	T _A	-40 ~ 85	°C
Storage Temperature (保存温度)	T _{STG}	-40 ~ 100	°C

Note: (备注)

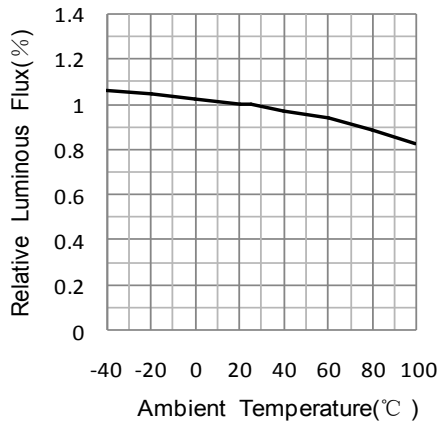
- 1/10 Duty cycle, 0.1ms pulse width. (脉宽0.1ms, 周期1/10)
2. The above forward voltage measurement allowance tolerance is ±0.1V. (以上所示电压测量误差±0.1V)

HL-PST-1608IR1C-L4

Typical optical characteristics curves 典型光学特性曲线

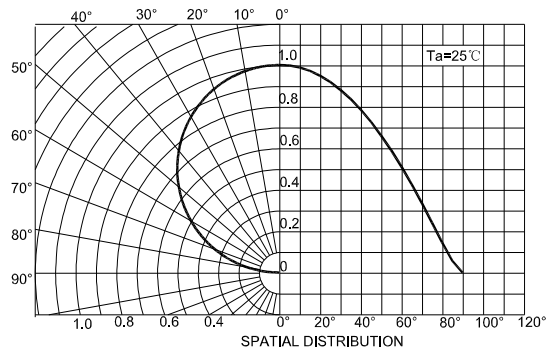
Ambient Temperature VS. Relative Intensity

环境温度与相对光强特性曲线



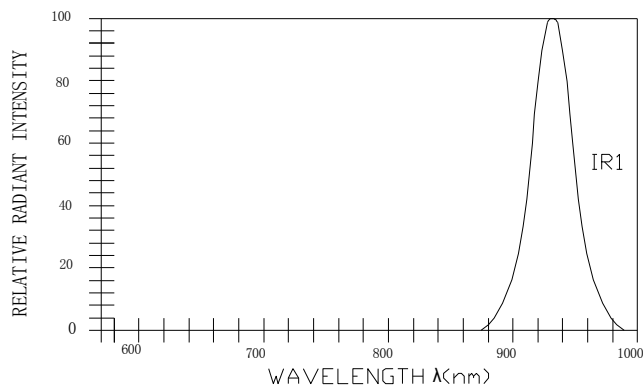
Radiation diagram

辐射图特性曲线



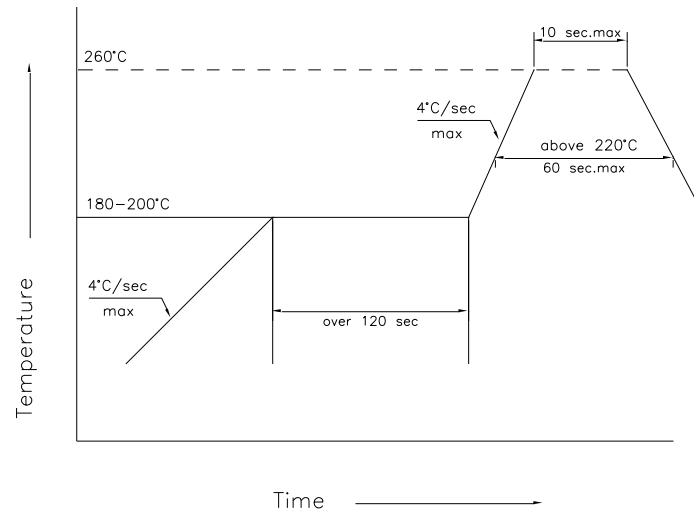
Relative spectral emission

相对光谱分布特性曲线



HL-PST-1608IR1C-L4

SMT Reflow Soldering Instructions SMT回流焊说明



- 1.Reflow soldering should not be done more than two times. 回流焊不可以做两次以上
- 2.When soldering , do not put stress on the LEDs during heating
当焊接时，不要在材料受热时用力压胶体表面

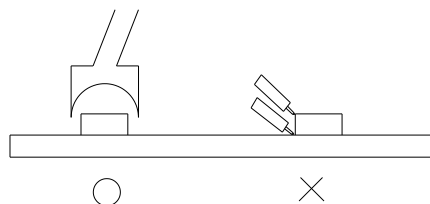
Soldering iron 烙铁焊接

- 1.When hand soldering, keep the temperature of iron below less 300°C less than 3 seconds
当手工焊接时，烙铁的温度必须小于300°C，时间不可超过3秒
- 2.The hand solder should be done only one times
手工焊接只可焊接一次

Repairing 修补

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or will not be damaged by repairing.

LED回流焊后不应该修复，当修复是不可避免时，必须使用双头烙铁（如下图），但必须事先确认此种方式会或不会损坏LED本身的特性。



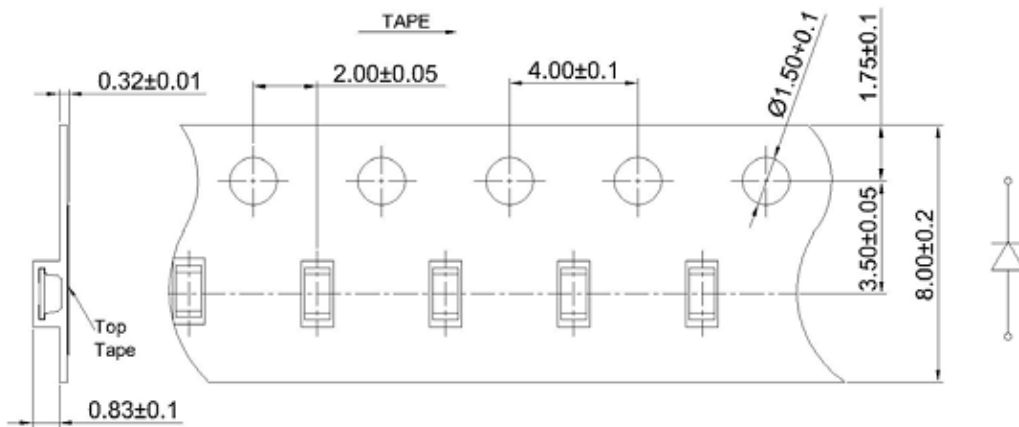
HL-PST-1608IR1C-L4

Label 标签

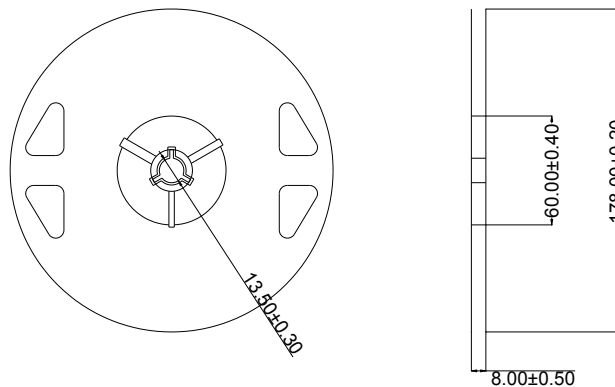
VF: Forward voltage rank 电压等级



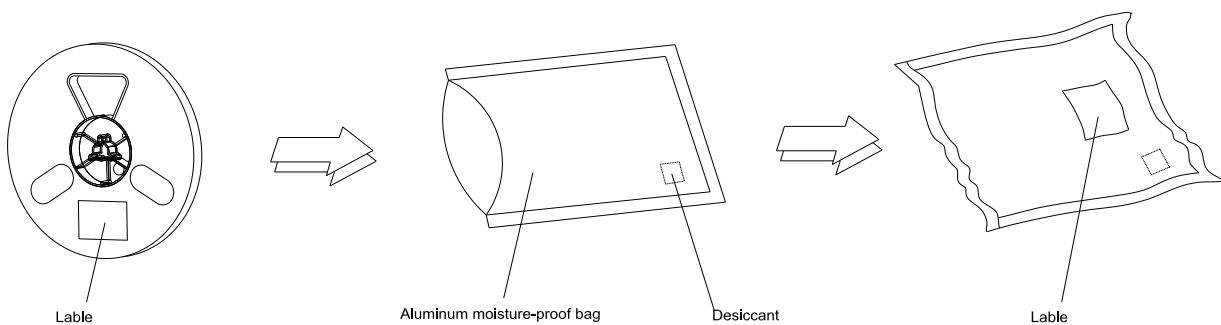
Tape Specifications (Units : mm) 载带规格 (单位: mm)



Reel Dimensions 卷轴尺寸



Moisture Resistant Packaging 防潮带包装



Note: The tolerances unless mentioned is ±0.1mm, Unit: mm 注: 标注公差为±0.1mm, 单位: mm